

Features

- Fast, high-density Field-Programmable Gate Arrays
 - Densities from 50k to 1M system gates
 - System performance up to 200 MHz
 - 66-MHz PCI Compliant
 - Hot-swappable for Compact PCI
- Multi-standard SelectIO™ interfaces
 - 16 high-performance interface standards
 - Connects directly to ZBTRAM devices
- Built-in clock-management circuitry
 - Four dedicated delay-locked loops (DLLs) for advanced clock control
 - Four primary low-skew global clock distribution nets, plus 24 secondary local clock nets
- Hierarchical memory system
 - LUTs configurable as 16-bit RAM, 32-bit RAM, 16-bit dual-ported RAM, or 16-bit Shift Register
 - Configurable synchronous dual-ported 4k-bit RAMs
 - Fast interfaces to external high-performance RAMs
- Flexible architecture that balances speed and density
 - Dedicated carry logic for high-speed arithmetic
 - Dedicated multiplier support
 - Cascade chain for wide-input functions
 - Abundant registers/latches with clock enable, and dual synchronous/asynchronous set and reset
 - Internal 3-state bussing
 - IEEE 1149.1 boundary-scan logic
 - Die-temperature sensor diode

- Supported by FPGA Foundation™ and Alliance Development Systems
 - Complete support for Unified Libraries, Relationally Placed Macros, and Design Manager
 - Wide selection of PC and workstation platforms
- SRAM-based in-system configuration
 - Unlimited re-programmability
 - Four programming modes
- 0.22 μ m 5-layer metal process
- 100% factory tested

Description

The Virtex FPGA family delivers high-performance, high-capacity programmable logic solutions. Dramatic increases in silicon efficiency result from optimizing the new architecture for place-and-route efficiency and exploiting an aggressive 5-layer-metal 0.22 μ m CMOS process. These advances make Virtex FPGAs powerful and flexible alternatives to mask-programmed gate arrays. The Virtex family comprises the nine members shown in [Table 1](#).

Building on experience gained from previous generations of FPGAs, the Virtex family represents a revolutionary step forward in programmable logic design. Combining a wide variety of programmable system features, a rich hierarchy of fast, flexible interconnect resources, and advanced process technology, the Virtex family delivers a high-speed and high-capacity programmable logic solution that enhances design flexibility while reducing time-to-market.

Table 1: Virtex Field-Programmable Gate Array Family Members

Device	System Gates	CLB Array	Logic Cells	Maximum Available I/O	Block RAM Bits	Maximum SelectRAM+™ Bits
XCV50	57,906	16x24	1,728	180	32,768	24,576
XCV100	108,904	20x30	2,700	180	40,960	38,400
XCV150	164,674	24x36	3,888	260	49,152	55,296
XCV200	236,666	28x42	5,292	284	57,344	75,264
XCV300	322,970	32x48	6,912	316	65,536	98,304
XCV400	468,252	40x60	10,800	404	81,920	153,600
XCV600	661,111	48x72	15,552	512	98,304	221,184
XCV800	888,439	56x84	21,168	512	114,688	301,056
XCV1000	1,124,022	64x96	27,648	512	131,072	393,216

Virtex Architecture

Virtex devices feature a flexible, regular architecture that comprises an array of configurable logic blocks (CLBs) surrounded by programmable input/output blocks (IOBs), all interconnected by a rich hierarchy of fast, versatile routing resources. The abundance of routing resources permits the Virtex family to accommodate even the largest and most complex designs.

Virtex FPGAs are SRAM-based, and are customized by loading configuration data into internal memory cells. In some modes, the FPGA reads its own configuration data from an external PROM (master serial mode). Otherwise, the configuration data is written into the FPGA (Select-MAP™, slave serial, and JTAG modes).

The standard Xilinx Foundation™ and Alliance Series™ Development systems deliver complete design support for Virtex, covering every aspect from behavioral and schematic entry, through simulation, automatic design translation and implementation, to the creation, downloading, and readback of a configuration bit stream.

Higher Performance

Virtex devices provide better performance than previous generations of FPGA. Designs can achieve synchronous system clock rates up to 200 MHz including I/O. Virtex inputs and outputs comply fully with PCI specifications, and interfaces can be implemented that operate at 33 MHz or 66 MHz. Additionally, Virtex supports the hot-swapping requirements of Compact PCI.

Xilinx thoroughly benchmarked the Virtex family. While performance is design-dependent, many designs operated internally at speeds in excess of 100 MHz and can achieve 200 MHz. **Table 2** shows performance data for representative circuits, using worst-case timing parameters.

Table 2: Performance for Common Circuit Functions

Function	Bits	Virtex -6
Register-to-Register		
Adder	16	5.0 ns
	64	7.2 ns
Pipelined Multiplier	8 x 8	5.1 ns
	16 x 16	6.0 ns
Address Decoder	16	4.4 ns
	64	6.4 ns
16:1 Multiplexer		5.4 ns
Parity Tree	9	4.1 ns
	18	5.0 ns
	36	6.9 ns
Chip-to-Chip		
HSTL Class IV		200 MHz
LVTTL, 16mA, fast slew		180 MHz

Virtex Device/Package Combinations and Maximum I/O

Table 3: Virtex Family Maximum User I/O by Device/Package (Excluding Dedicated Clock Pins)

Package	XCV50	XCV100	XCV150	XCV200	XCV300	XCV400	XCV600	XCV800	XCV1000
CS144	94	94							
TQ144	98	98							
PQ240	166	166	166	166	166				
HQ240						166	166	166	
BG256	180	180	180	180					
BG352			260	260	260				
BG432					316	316	316	316	
BG560						404	404	404	404
FG256	176	176	176	176					
FG456			260	284	312				
FG676						404	444	444	
FG680							512	512	512

Virtex Ordering Information

Example: **XCV300 -6 PQ 240 C**

Device Type

Speed Grade

-4

-5

-6

Temperature Range

C = Commercial ($T_J = 0^{\circ}\text{C}$ to $+85^{\circ}\text{C}$)

I = Industrial ($T_J = -40^{\circ}\text{C}$ to $+100^{\circ}\text{C}$)

Number of Pins

Package Type

BG = Ball Grid Array

FG = Fine-pitch Ball Grid Array

PQ = Plastic Quad Flat Pack

HQ = High Heat Dissipation QFP

TQ = Thin Quad Flat Pack

CS = Chip-scale Package

Figure 1: Virtex Ordering Information

Revision History

Date	Version	Revision
11/98	1.0	Initial Xilinx release.
01/99	1.2	Updated package drawings and specs.
02/99	1.3	Update of package drawings, updated specifications.
05/99	1.4	Addition of package drawings and specifications.
05/99	1.5	Replaced FG 676 & FG680 package drawings.
07/99	1.6	Changed Boundary Scan Information and changed Figure 11, Boundary Scan Bit Sequence. Updated IOB Input & Output delays. Added Capacitance info for different I/O Standards. Added 5 V tolerant information. Added DLL Parameters and waveforms and new Pin-to-pin Input and Output Parameter tables for Global Clock Input to Output and Setup and Hold. Changed Configuration Information including Figures 12, 14, 17 & 19. Added device-dependent listings for quiescent currents ICCINTQ and ICCOQ. Updated IOB Input and Output Delays based on default standard of LVTTTL, 12 mA, Fast Slew Rate. Added IOB Input Switching Characteristics Standard Adjustments.
09/99	1.7	Speed grade update to preliminary status, Power-on specification and Clock-to-Out Minimums additions, "0" hold time listing explanation, quiescent current listing update, and Figure 6 ADDRA input label correction. Added T_{IJITCC} parameter, changed T_{OJIT} to T_{OPHASE} .
01/00	1.8	Update to speed.txt file 1.96. Corrections for CRs 111036, 111137, 112697, 115479, 117153, 117154, and 117612. Modified notes for Recommended Operating Conditions (voltage and temperature). Changed Bank information for V_{CCO} in CS144 package on p.43.
01/00	1.9	Updated DLL Jitter Parameter table and waveforms, added Delay Measurement Methodology table for different I/O standards, changed buffered Hex line info and Input/Output Timing measurement notes.
03/00	2.0	New TBCKO values; corrected FG680 package connection drawing; new note about status of CCLK pin after configuration.
05/00	2.1	Modified "Pins not listed ..." statement. Speed grade update to Final status.
05/00	2.2	Modified Table 18.
09/00	2.3	- Added XCV400 values to table under Minimum Clock-to-Out for Virtex Devices. - Corrected Units column in table under IOB Input Switching Characteristics. - Added values to table under CLB SelectRAM Switching Characteristics.
10/00	2.4	- Corrected Pinout information for devices in the BG256, BG432, and BG560 packages in Table 18. - Corrected BG256 Pin Function Diagram.
04/01	2.5	- Revised minimums for Global Clock Set-Up and Hold for LVTTTL Standard, with DLL. - Converted file to modularized format. See Virtex Data Sheet section.

Virtex Data Sheet

The Virtex Data Sheet contains the following modules:

- DS003-1, Virtex 2.5V FPGAs:
Introduction and Ordering Information (Module 1)
- DS003-2, Virtex 2.5V FPGAs:
[Functional Description \(Module 2\)](#)
- DS003-3, Virtex 2.5V FPGAs:
[DC and Switching Characteristics \(Module 3\)](#)
- DS003-4, Virtex 2.5V FPGAs:
[Pinout Tables \(Module 4\)](#)